What is claimed is:

1. A manufacturing method for a device in which some or all of plural elements formed on a first substrate, are transferred to a second substrate, and some or all of the transferred elements are used to manufacture the device, the method comprising:

a first process for forming an separation layer on said first substrate;

a second process for forming many elements on said separation layer;

a third process for adhering the elements to be transferred on said first substrate, to said second substrate via an adhesive layer;

a fourth process for exerting a force acting in a direction to separate said first substrate and said second substrate on the separation layer between said first substrate and said second substrate from one edge of those substrates, to execute exfoliation in the layer and/or on an interface of the separation layer; and

a fifth process for separating said first substrate from which the transfer of elements has been completed, from said second substrate.

2. A manufacturing method for a device according to claim 1, wherein the transfer of the elements from said first substrate to said second substrate comprising a step of collectively transferring all the elements formed on said first substrate.

3. A manufacturing method for a device according to one of claim 1 and claim 2, further comprising:

a sixth process for forming after separating said first substrate from said second substrate, a thin film element providing substrate by providing a heat fusion sheet containing heat sealing adhesive on said elements which have been transferred to said

second substrate;

a seventh process for superposing a final substrate so that it contacts with said heat fusion sheet of said thin film element providing substrate, selectively irradiating light only on the area of said elements to be transferred, and adhering only said elements to be transferred onto the final substrate for device forming; and

an eighth process for removing said thin film element providing substrate having untransferred elements, from the final substrate to which said elements have been transferred.

4. A manufacturing method for a device according to one of claims 1 through 3, having a pre-exfoliation process between said third process and said fourth process, for selectively irradiating light onto said separation layer between said elements to be transferred and said first substrate, to execute exfoliation in the layer and/or on the interface of said separation layer.

5. A manufacturing method for a device according to one of claims 1 through 4, wherein said fourth process is performed by inserting a sharp edge body into one edge between said first substrate and said second substrate.

6. A manufacturing method for a device according to one of claims 1 through 4, wherein said fourth process is performed by injecting a high pressure gas into one edge between said first substrate and said second substrate.

7. A manufacturing method for a device according to one of claims 1 through 4, wherein said fourth process is performed by injecting a liquid into one edge between said

first substrate and said second substrate.

8. A manufacturing method for a device according to one of claims 1 through 4, wherein said fourth process is performed by moving one of the edges of said first substrate and said second substrate in a direction to separate from the other of the edges of said first substrate and said second substrate.

9. A manufacturing method for a device according to any one of claims 1 through 4, wherein said a thermal expansion material is provided in one edge of said separation layer when forming said separation layer in said first process, and said fourth process is performed by thermal expansion of said thermal expansion material by heat treatment.

10. A manufacturing method for a device according to any one of claim 1 through claim 4, wherein said fourth process is performed by laser ablating said separation layer by irradiating laser light onto one edge between said first substrate and said second substrate.

11. A device obtained by a manufacturing method according to one of claim 1 through claim 10. .

12. An electro-optic device provided with devices according to claim 11.

13. An electronic equipment provided with the devices according to claim 11.